

OvationONS™ Laser Navigation Sensors

Features

- Hardware resolution to 3200 cpi
 - Ability to maintain full resolution at speeds up to 50 ips
- Multiple resolution control modes, including:
 - Continuously variable resolution
 - Independent control of resolution in the x and y direction
- PC cursor speeds to 160,000 cps
- Market-leading 40 kHz positioning sampling rate
- Superior tracking performance
- Integrated single package 850 nm VCSEL and laser driver
 - No power calibration or optical alignment required
 - Fault-tolerant drive circuitry for Class 1 eye safety compliance
 - Improved ESD tolerance: 2 kV versus 200V typical for standalone laser
 - Self-aligning snap-on lens for ease of assembly
- Peripheral interface:
 - 4-wire SPI port
 - Native 16-bit x and y directional reports from the sensor
- Power:
 - Wide operating voltage range: 2.7V to 3.6V
 - Self-adjusting nap and sleep modes
 - Hibernate mode for USB suspend requirements

Description

The OvationONS™ CYONS1001x laser navigation sensors are breakthrough solutions for wired and wireless mice, and precision motion-sensing applications. Built around Cypress Semiconductor's patented OptiCheck™ laser technology, these devices offer a variety of significant advantages.

Unlike any other laser-based sensor on the market today, the CYONS1001x sensors provide:

- the unique ability to maintain full resolution at speeds up to 50 inches per second (ips)
- low power consumption regardless of tracking speed or resolution
- an unprecedented 40 kHz positioning sampling rate



As a result, the CYONS1001x sensors deliver fast, precise, responsive tracking, without the trade offs between power and performance that characterize traditional image-correlation sensors.

Moreover, the CYONS1001x sensors are strategically designed to simplify assembly, reduce manufacturing costs, and improve yield. The sensor IC, vertical-cavity surface emitting laser (VCSEL), and laser driver are integrated in a single 8x8 QFN package with a self-aligning snap-on lens. Laser output power is calibrated before shipment to meet eye-safety standards. Consequently, there is no need for laser handling, laser power calibration, or optical alignment.

Five versions of the CYONS1001x sensor are available, each with features designed for its target application. Optimized for gaming and other specialized high-performance applications, the CYONS1001U, CYONS1001G, and CYONS1001 combine unrivalled effective cursor speeds with continuously variable resolution to 3200 counts per inch (cpi) and independent resolution control in the x and y directions. The general purpose CYONS1001L and CYONS1001T, designed for desktop mouse and trackball applications, support two self-adjusting power down modes for extended battery life.

All CYONS1001x sensors provide maximized counts per second, minimized latency to motion changes, and optimum signal quality in the detection of laser-speckle signatures over a wide range of surfaces, offering users the ultimate experience of fast, precision tracking.

Table 1. OvationONS CYONS1001x Laser Navigation Sensors

Parameter	CYONS1001U	CYONS1001G	CYONS1001	CYONS1001L	CYONS1001T
Maximum resolution	3200 cpi	2800 cpi	2400 cpi	1200 cpi	1150 cpi
Maximum speed	50 ips	50 ips	45 ips	20 ips	20 ips
Resolution control	Continuous	Continuous	Continuous	400, 800, 1200 cpi	50 cpi steps
Maximum cursor speed	160,000	140,000	120,000	24,000	23,000
Maximum position sampling rate	40 kHz	40 kHz	40 kHz	40 kHz	40 kHz
Acceleration	10G	10G	10G	8G	8G
All sensors sold with the CYONSLENS1001 lens.					

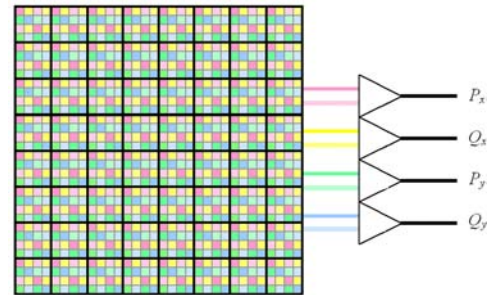
Applications

- CYONS1001U and CYONS1001G are the ideal solutions for high speed, high performance gaming mouse applications.
- CYONS1001 is designed to enable high precision and high accuracy tracking performance. The device is ideal for industrial control, noncontact digital measurement tools, graphics design peripherals, and other high precision motion-sensing applications.
- CYONS1001L is designed for desktop and mobile mouse applications.
- CYONS1001T is an elegant solution for low power, high precision trackball applications.

OptiCheck™ Technology

The OvationONS sensors use Cypress Semiconductor’s patented OptiCheck technology — a fundamentally different approach to laser navigation sensing. Instead of image capture and correlation, OptiCheck uses an “Optical Checkerboard” or array of light-sensitive elements connected in a patented, 2D comb detector configuration¹. The outputs of the detector are amplified and combined in a unique arrangement to form four data outputs that completely describe the motion of the sensor. These four outputs are digitized and sent to a small digital signal processor to generate x and y location displacement data. [Figure 1](#) shows the interconnection of the comb detector elements and the resulting four outputs.

Figure 1. OptiCheck Optical Checkerboard



There are three key advantages to the OptiCheck approach:

- First, power consumption does not increase with an increase in tracking speed. OptiCheck requires only four data inputs to calculate x and y displacement, compared to the hundreds of inputs typically required for image correlation. OptiCheck therefore provides a much more efficient calculation. This increase in efficiency means the signal processing blocks have a negligible impact on power consumption, resulting in a system where current draw is nearly independent of speed.
- Second, tracking speed is independent of resolution. OptiCheck’s processing requirements are independent of sensor resolution. This enables simpler and lower cost scaling for products that require both high speed and high resolution tracking performance.
- Third, the unique signal processing method employed by OptiCheck sensors enables continuously variable native resolution in the x and y directions independently. This unique capability offers application designers immense flexibility and freedom.

Note

1. U.S. Patent No. 7,138,620, entitled “Two-dimensional Motion Sensor”, describes aspects of this technology.

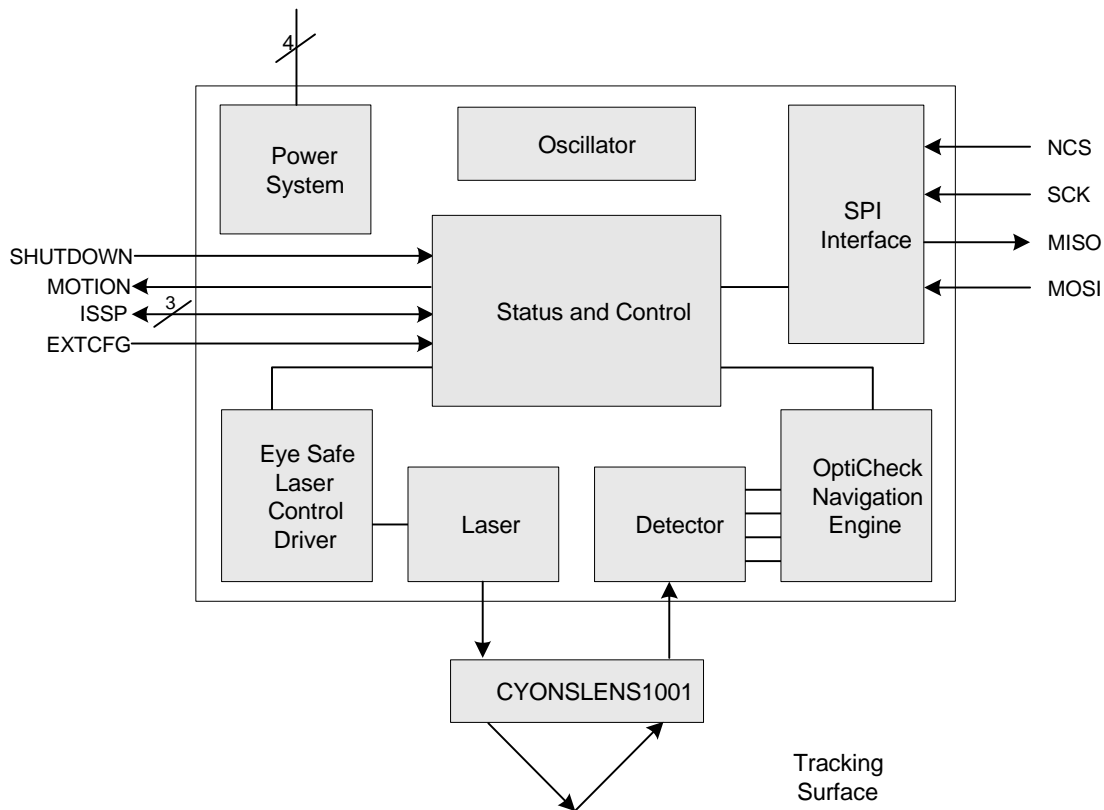
Functional Description

The CYONS1001x sensor is a two piece solution: a sensor IC and VCSEL in an 8x8 QFN package, and a self-aligning snap-on lens. The optical system consists of a precision aperture and an optical lens. Laser speckle signals are processed by the optical system and transferred to the detector for signal processing.

In addition to an integrated optical detector and signal processor, the CYONS1001x sensor package includes integrated laser driver circuitry and laser fault detection circuitry for IEC/EN 60825-1 Class 1 eye safety compliance. An on-chip oscillator provides system timing without the need for an external crystal.

Logic Block Diagram

Figure 2. CYONS1001x Block Diagram



Pinouts

Figure 3. CYONS1001x Package Pinout

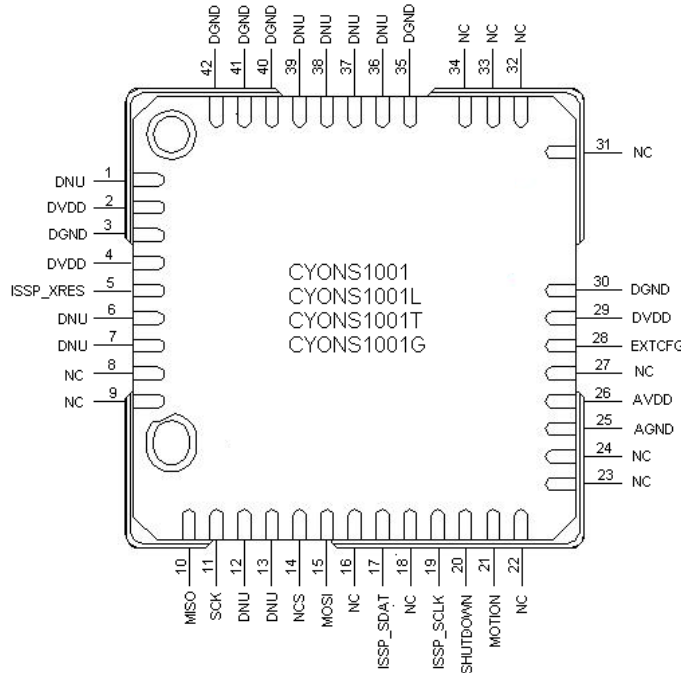


Table 2. CYONS1001x Pin Description

Pin Number	Signal Name	Type	Number of Pins	Function
14	NCS	I	1	SPI chip select
11	SCK	I	1	SPI serial clock input
10	MISO (Master In/Slave Out)	O	1	SPI output
15	MOSI (Master Out/Slave In)	I	1	SPI input
20	SHUTDOWN	I	1	Enter hibernate mode
21	MOTION	O	1	Motion detect; active HIGH output
28	EXTCFG	I	1	External configuration for factory test
26	AVDD	Power	1	Analog supply voltage
2,4,29	DVDD	Power	3	Digital supply voltage
25	AGND	Ground	1	Analog ground
3, 30	DGND	Ground	2	Digital ground
1, 6, 7, 12, 13, 36, 37, 38, 39	DNU		9	Do Not Use
8, 9, 16, 18, 22, 23, 24, 27, 31, 32, 33, 34	NC		12	No connect
35, 40, 41, 42	Tie to DGND		4	Must be connected to DGND
E-PAD (case bottom)	DGND	Ground	1	Digital ground
19 ^[2]	ISSP_SCLK	IO	1	ISSP serial clock
17 ^[2]	ISSP_SDAT	IO	1	ISSP serial data IO
5 ^[2]	ISSP_XRES	IO	1	ISSP reset drive

Note

2. Pins 5, 17, and 19 are solely for in-system firmware upgrades.

Technical Specifications

Table 3. Absolute Maximum Ratings

Parameter	Min	Typ	Max	Unit	Notes
Storage temperature	-40		85	°C	Case temperature
Operating temperature	-15		55	°C	Case temperature
Lead solder temperature			260	°C	3 cycles with 20 second dwell at peak temperature
Supply voltage	-0.5		3.7	V	
ESD			2	kV	All pins, HBM MIL 883 method 3015
Input voltage	-0.5		$V_{DVDD}+0.5$	V	
Latch up current			100	mA	

Table 4. Operating Conditions

Parameter	Min	Typ	Max	Unit	Notes
Operating temperature	5		45	°C	Operation beyond this range may cause laser to exceed Class 1 limits
Power supply voltage	2.7		3.6	V	Operation beyond this range may cause laser to exceed Class 1 limits
Power supply rise time	100			µs	
Supply noise – AVDD (sinusoidal)			25	mV p-p	10 kHz–50 MHz
Supply noise – DVDD (sinusoidal)			100	mV p-p	10 kHz–50 MHz
Serial port clock frequency	0.5		2.0	MHz	Active drive, 50% duty cycle
Distance from PCB to tracking surface	12.53	12.78	13.03	mm	Deviation from nominal adversely impacts lift detection and tracking
Load capacitance			100	pF	MOTION, MISO

Table 5. DC Electrical Characteristics

At 25°C, 3.3V unless otherwise specified

Parameter	Min	Typ	Max	Unit	Notes
DC current in tracking mode		13.5	15.5	mA	Full speed motion
DC current in nap mode		3.0	4.5	mA	After 4 seconds of inactivity
DC current in sleep mode		375	550	µA	After 30 seconds of inactivity
DC current in hibernate mode		45	70	µA	After receiving SHUTDOWN signal from controller
Input low voltage			0.8	V	
Input high voltage	$0.7V_{DVDD}$			V	
Input hysteresis		100		mV	
Input leakage current		±1	±10	µA	MOSI, NCS
Output low voltage			0.7	V	MISO, MOTION
Output high voltage	$V_{DVDD}-0.7$			V	
Input capacitance			10	pF	MOSI, NCS

Table 6. AC Electrical Characteristics

At 25°C, 3.3V unless otherwise specified

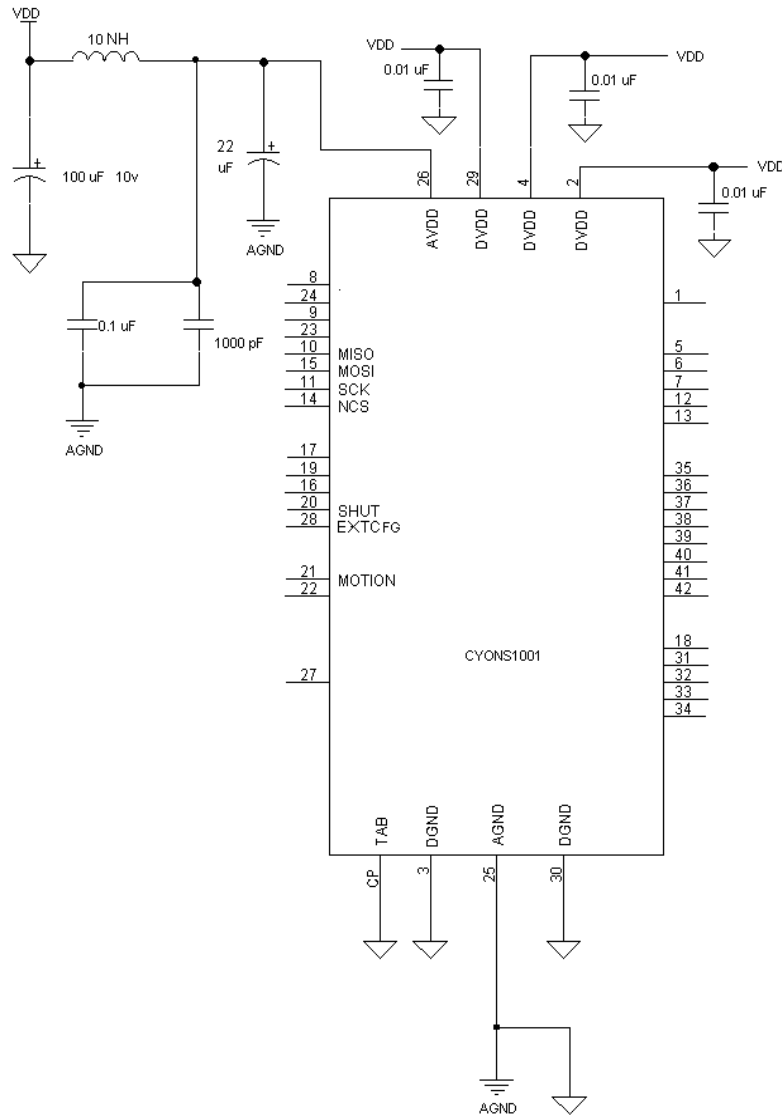
Parameter	Min	Typ	Max	Unit	Notes
Reset delay			100	ms	
Hibernate			10	ms	From SHUTDOWN high to low current
Wake from hibernate			20	ms	From SHUTDOWN low to normal operation
MISO rise time		150	300	ns	100 pF load
MISO fall time		150	300	ns	100 pF load
MISO delay after SCK			120	ns	
MISO hold time	0.5			μs	
MOSI hold time	200			ns	
MOSI setup time	120			ns	
Delay between SPI commands					
after write command t_{CMD_1}	30			μs	Falling edge of SCK to rising edge of SCK for next command
after read/burst read command t_{CMD_2}	300			μs	Falling edge of SCK to rising edge of SCK for next command
Delay within SPI commands					
after command byte $t_{SPI_DELAY_1}$	400			μs	All commands
between data bytes $t_{SPI_DELAY_2}$	20			μs	Burst read command
from addr to data byte $t_{SPI_DELAY_3}$ $t_{SPI_DELAY_4}$	20 100			μs μs	End of addr byte to start of data byte Write command Read command
NCS setup time - t_{NCS_SU}	120			ns	All commands
NCS hold time - t_{NCS_HOLD}	500			ns	All commands
NCS to MISO high Z			20	μs	5 pF load, Thevenin load
MOTION rise time		150	300	ns	100 pF load
MOTION fall time		150	300	ns	100 pF load

Power and Ground Interface

The CYONS1001x sensors are powered by a single 2.7–3.6V power supply. Two external components are required to isolate the analog and digital sections of the sensor and ensure proper analog power supply ramp time: a 22 μF capacitor and a 10 nH inductor. Place decoupling capacitors at all power pins as close to the pin as possible.

Figure 4 shows the recommended power and ground circuitry. Note that to meet laser safety requirements, the power supply voltage supplied to the sensor circuit must meet the operating conditions requirements specified in this document. Additionally, increasing the laser output power by any other means (hardware, firmware, or otherwise) can result in a violation of the Class 1 safety limit.

Figure 4. Recommended Power and Ground Circuitry



Power Management

The CYONS1001x sensors are equipped with power management features designed to meet the needs of their target applications. The CYONS1001L and CYONS1001T sensors, which target general purpose tracking applications such as wireless mice, offer two power saving sleep modes that extend battery life, and an ultra low power hibernate mode that is used to meet USB suspend requirements. The CYONS1001, CYONS1001G, and CYONS1001U sensors are optimized for high performance applications that require fast response at all times; therefore, these devices only support hibernate mode.

The operational modes supported by the CYONS1001x sensors are summarized in [Table 7](#). The current consumption of each mode is listed in [Table 5](#) on page 5.

Table 7. Summary of CYONS1001x Operational Modes

Mode	CYONS1001, 1001G, 1001U	CYONS 1001L, 1001T
Tracking	Yes	Yes
Nap	No	Yes
Sleep	No	Yes
Hibernate	Yes	Yes

Tracking Mode

In tracking mode, the sensor is in motion and tracking x/y changes. Tracking mode consumes the most power, with fast motion drawing slightly more current than slow motion. After approximately 4 seconds of inactivity, the sensor automatically switches to nap mode.

Nap Mode

In nap mode, the sensor can detect gross motion. If motion is detected, the sensor switches to tracking mode within 20 ms. If motion is not detected for 30 seconds after entering nap mode, the sensor automatically switches to sleep mode.

Sleep Mode

In sleep mode, the sensor can also detect gross motion. If motion is detected, the sensor enters tracking mode within 250 ms. If motion is not detected, the sensor remains in sleep mode indefinitely.

Hibernate Mode

The controller can place the sensor in hibernate mode by asserting the SHUTDOWN pin. In this state, the sensor cannot detect motion, and can only be activated by resetting the SHUTDOWN pin to LOW. Startup time from hibernate mode to full tracking capability is 20 ms max.

Passive Power Management

The CYONS1001L and CYONS1001T sensors are ideal for passive power management. Unlike other laser sensors, these devices control their own low power modes, freeing the application designer from concerns about power minimization. No additional firmware is required to take advantage of their self-adjusting power-saving nap and sleep modes.

Active Power Management

For applications requiring further power reduction, mouse firmware can use the SHUTDOWN and MOTION pins to implement active power management. This means the controller actively switches the sensor between tracking and hibernate modes to reap the benefit of low current draw during hibernate mode.

A typical requirement for a mouse is that mouse movement must be able to wake the system from a low power operating state. Though the sensor is unable to detect motion in hibernate state, firmware can be designed to periodically check for motion by temporarily bringing the sensor out of hibernation. A recommended approach to active power management is as follows:

1. Choose a motion-check period, such as once per second. Longer periods save more power, but also result in longer delays in detecting motion.
2. Assert the SHUTDOWN pin to put the sensor in hibernate mode.
3. At the start of each motion-check period, deassert the SHUTDOWN line, then wait until the sensor sets the MOTION line high (20 ms or less).
4. Send two read tracking data commands to the sensor, ensuring sufficient delay between the commands. The sensor reports zeroes in response to the first command to avoid sending spurious data. The second report has valid x-y data.
5. If the data is two counts or more for either x or y, the sensor has been moved and the controller must initiate its wakeup sequence. If the data is 1 count or less for both x and y, the sensor has not been moved and the controller can reassert SHUTDOWN until the next motion-check period.

Resolution Control Capabilities

The CYONS1001x sensors support a variety of resolution control modes that offer users both precision tracking and flexibility. The resolution control capabilities of each sensor are summarized in [Table 8](#). The various resolution control modes are described in the following sections.

Standard Resolution Control

In standard control mode, resolution is adjusted in increments of 200 or 400 cpi, depending on the sensor.

X/Y Resolution Control

In x/y resolution control mode, the x-direction and y-direction resolution are independent: they need not be set to the same value. Resolution in either direction is adjusted in increments of 50 cpi.

Fine Resolution Control

Fine control mode enables continuously variable resolution in increments of less than 1 cpi.

Setting Sensor Resolution

Sensor resolution is controlled by the change resolution command described on page 11.

- Standard resolution control requires a single change resolution command to change the resolution in both the x and y direction.
- X/Y resolution control requires a separate change resolution command for each direction.
- Fine resolution control requires two change resolution commands to specify the resolution. In both commands, the two most significant bits select the resolution control mode. In the first command, bits 5-0 provide the first half of the resolution code. In the second command, bits 5-0 provide the second half of the resolution code.

Table 8. Resolution Control Capabilities of CYONS1001x Sensors

Sensor	Minimum Resolution	Maximum Resolution	Standard Resolution Control	X/Y Resolution Control	Fine Resolution Control
CYONS1001L	400 cpi	1200 cpi	400 cpi steps	–	–
CYONS1001T	50 cpi	1150 cpi	–	50 cpi steps	–
CYONS1001	400 cpi	2400 cpi	200 cpi steps	50 cpi steps	<1 cpi steps
CYONS 1001G	400 cpi	2800 cpi	200 cpi steps	50 cpi steps	<1 cpi steps
CYONS 1001U	400 cpi	3200 cpi	200 cpi steps	50 cpi steps	<1 cpi steps

SPI Interface

SPI Interface Configuration

The main interface to the CYONS1001x sensor is a 4-pin SPI interface. The sensor is an SPI slave, and the external controller is the master. If the sensor is the only slave device, the controller can hold the NCS pin low at all times.

The sensor SPI bus is configured as follows:

- Bit order is MSB first
- The SPI bus clock input (SCK) must be between 500 kHz and 2 MHz
- CPOL = 0, the clock idle state is low
- CPHA = 0, data is registered as input on the leading edge of SCK and output on the trailing edge of the SCK

The sensor can process SPI commands when the MOTION pin is asserted by the sensor. The sensor cannot process SPI commands in nap, sleep, or hibernate mode.

SPI Interface Commands

Table 9 shows the format of the commands the external controller can issue to the sensor. Except for the change resolution and read resolution commands, the commands are identical for all for all CYONS1001x sensors.

The commands are described in the following sections. Timing diagrams for the commands are shown on page 13.

Read Tracking Data Command

The read tracking data command reads four bytes of x/y axis location information in a single long transaction. To reduce the

overhead of this frequent command, no address byte is required, only a command byte.

Tracking data is reported as relative movement since the last tracking data read. The tracking data is reported in two's complement format. Each time tracking data is read, the internal accumulators for both the x-axis and the y-axis are reset to zero.

Soft Reset Command

The soft reset command forces the sensor into a soft reset. The reset takes the same amount of time as a power on reset of the sensor chip, so the external controller must wait approximately 100 ms before the sensor can respond to further commands.

Test Write Command

The test write command writes a data byte to sensor memory, where it is read back by the test read command. These commands enable the developer to test the SPI interface between the sensor and external controller.

Test Read Command

The test read command reads the test write data byte from sensor memory. If a test write command has not been issued before the test read command, the value returned is undefined.

Read Firmware ID Command

The read firmware ID command enables the controller to read a sensor firmware ID byte, allowing the system to maintain version control of firmware updates. The command is implemented as a read to the firmware ID address of the sensor. The byte returned by the sensor is a unique identifier of the firmware. Other than that, it is not structured.

Table 9. SPI Command Formats

SPI Command	Request from Master			Response from Slave	t _{SPI DELAY_1} (min)	t _{SPI DELAY_2} (min)
	Command byte	Address byte	Data byte			
Read tracking data	0x80	None	None	<x_cnt_high_byte> <x_cnt_low_byte> <y_cnt_high_byte> <y_cnt_low_byte>	400 μs	20 μs
Soft reset	0x02	0xE0	0x01	No response	400 μs	20 μs
Change resolution	0x02	0x1A	<data_byte>	No response	400 μs	20 μs
Read resolution	0x82	0x1A	None	<data_byte>	400 μs	100 μs
Test write	0x02	0x1C	0xFF	No response	400 μs	20 μs
Test read	0x82	0x1C	None	<data_byte>	400 μs	100 μs
Read firmware ID	0x82	0xFF	None	<data_byte>	400 μs	100 μs
Read product ID	0x82	0xFE	None	0x0F:CYONS1001 0x0A:CYONS1001L 0x05:CYONS1001T 0x0B:CYONS1001G 0x0C:CYONS1001U All others reserved	400 μs	100 μs
Read signal level	0x82	0x5B	None	<data_byte>	400 μs	100 μs

Read Product ID Command

The read product ID command enables the controller to read a sensor product ID byte. The command is implemented as a read to the product ID address of the sensor. The byte returned by the sensor is a unique identifier of the product ID. Other than that, it is not structured.

Read Signal Level Command

The read signal level command enables the controller to read an indicator of the strength of the optical signal received by the sensor. The signal level returned by the sensor is not calibrated; yet, it can provide a useful measurement of signal level during system development.

Change Resolution Command

The change resolution command enables the external controller to select the resolution of the tracking data reported by the sensor. The command consists of command byte, address byte, and data byte. The command and address bytes are the same for all CYONS1001x sensors; however, because the CYONS1001x have different resolution control capabilities, the interpretation of the data byte varies by sensor.

Table 10 through Table 14 describe the configuration of the change resolution data byte for each CYONS1001x sensor. For a description of the resolution control modes, see “Resolution Control Capabilities” on page 9.

Read Resolution Command

The read resolution command reads the current resolution setting of the sensor. The sensor responds with a data byte that matches the data byte in the last valid change resolution command. The interpretation of the data byte in the sensor’s response to the read resolution command depends on the sensor and the resolution control mode the sensor is using. Table 10 through Table 13 describe the data bytes for each sensor.

Because the response from the sensor includes only a single data byte and some resolution settings are specified by two data bytes, the controller must use a write-read, write-read sequence to access the two bytes required to specify resolution in x/y resolution control mode or fine control mode.

if a read resolution command is sent before a change resolution command, the sensors respond with their default setting.

Table 10. CYONS1001L Change Resolution Data Byte

Bit	Function
7-6	00 = Standard resolution mode
5-0	Sets resolution from 400 to 1200 cpi 000001 = 1 = 400 cpi 000010 = 2 = 800 cpi 000011 = 3 = 1200 cpi

Table 11. CYONS1001T Change Resolution Data Byte

Bit	Function
7-6	Selects x or y direction ^[3] 01 = Change y direction resolution 10 = Change x direction resolution
5-0	Sets resolution in either the x or y direction from 50 to 1150 cpi 000001 = 1 = 50 cpi 000010 = 2 = 100 cpi ...etc... 010111 = 23 = 1150 cpi

Table 12. CYONS1001 Change Resolution Data Byte

Bit	Function
7-6	Selects resolution control mode: 00 = Standard resolution control 01 = Change y direction resolution 10 = Change x direction resolution 11 = Fine resolution control
5-0	In standard resolution mode: Sets resolution from 400 to 2400 cpi. 000010 = 2= 400 cpi 000011 = 3= 600 cpi ...etc.... 001100 = 12 = 2400 cpi In x/y resolution mode: ^[4] Sets resolution in either the x or y direction from 400 to 2400 cpi. 001000 = 8 = 400 cpi 001001 = 9 = 450 cpi ...etc.... 110000 = 48 = 2400 cpi In fine control mode: ^[5] Sets resolution from 400 to 2400 cpi in steps of 0.78125 dpi. 001000 000000 = 512 = 400 cpi 001000 000001 = 513 = 401 cpi ...etc.... 110000 000000 = 3072 = 2400 cpi

Notes

- The CYONS1001T only supports the x/y resolution control mode. A single change resolution command changes the resolution in either the x direction or y direction. Two commands are required to change the resolution in both directions.
- In x/y resolution control mode, a single change resolution command changes the resolution in either the x direction or y direction. Two commands are required to change the resolution in both directions.
- Fine resolution control mode requires two change resolution commands. In both commands, the first two bits select the resolution control mode. In the first command, bits 5-0 provide the first half of the resolution code. In the second command, bits 5-0 provide the second half of the resolution code.

Table 13. CYONS1001G Change Resolution Data Byte

Bit	Function
7-6	Selects resolution control mode: 00 = Standard resolution control 01 = Change y-direction resolution 10 = Change x-direction resolution 11 = Fine resolution control
5-0	In standard resolution mode: Selects resolution from 400 to 2800 cpi. 000010 = 2= 400 cpi 000011 = 3= 600 cpi ...etc.... 001110 = 14 = 2800 cpi In x/y resolution mode: ^[4] Sets resolution in either the x or y direction from 400 to 2800 cpi. 001000 = 8 = 400 cpi 001001 = 9 = 450 cpi ...etc.... 111000 = 56= 2800 cpi In fine control mode: ^[5] Sets resolution from 400 to 2800 cpi in steps of 0.78125 dpi. 001000 000000 = 512 = 400 cpi 001000 000001 = 513 = 401 cpi ...etc.... 111000 000000 = 3584 = 2800 cpi

Table 14. CYONS1001U Change Resolution Data Byte

Bit	Function
7-6	Selects resolution control mode: 00 = Standard resolution control 01 = Change y-direction resolution 10 = Change x-direction resolution 11 = Fine resolution control
5-0	In standard resolution mode: Selects resolution from 400 to 3200 cpi. 000010 = 2= 400 cpi 000011 = 3= 600 cpi ...etc.... 010000 = 16 = 3200 cpi In x/y resolution mode: ^[4] Sets resolution in either the x or y direction from 400 to 3150 cpi. 001000 = 8 = 400 cpi 001001 = 9 = 450 cpi ...etc.... 111111 = 63= 3150 cpi In fine control mode: ^[5] Sets resolution from 400 to 3199 cpi in steps of 0.78125 dpi. 001000 000000 = 512 = 400 cpi 001000 000001 = 513 = 401 cpi ...etc.... 111111 111111 = 4095 = 3199 cpi

SPI Interface Timing

Figure 5. Read Tracking Data Command Timing (Burst Read)

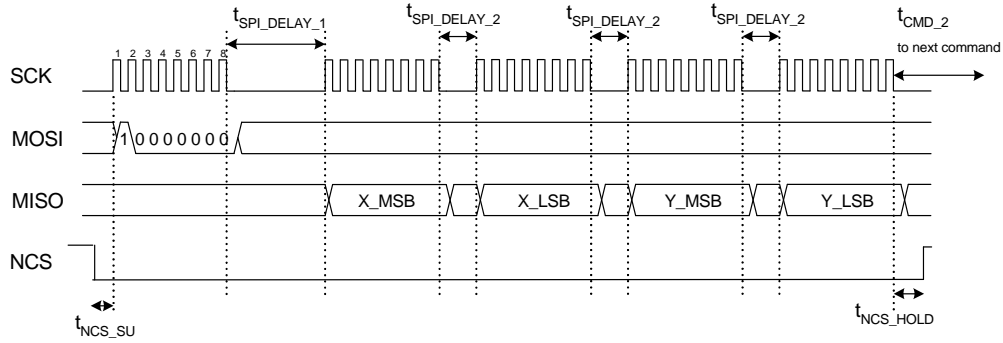


Figure 6. Timing for SPI Write Operations

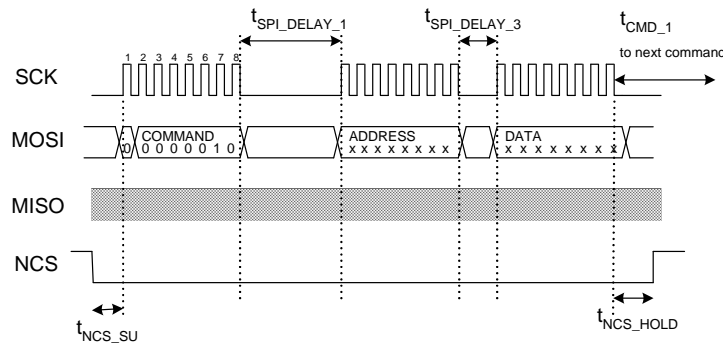
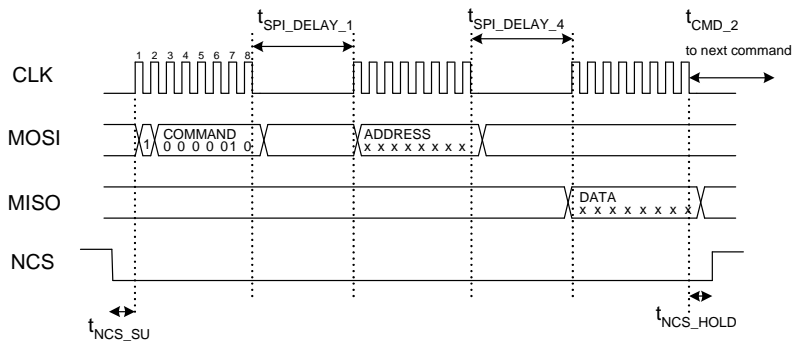


Figure 7. Timing for SPI Read Operations



SHUTDOWN, MOTION, and EXTCFG Pins

SHUTDOWN Pin

The SHUTDOWN pin enables hibernate mode — an ultra low power state in which the sensor cannot detect motion. When the SHUTDOWN pin is asserted, the sensor quickly powers down and remains powered down until the pin is deasserted. When the SHUTDOWN pin is deasserted, the sensor returns to the default power up state after an internal wakeup sequence. Startup time from deassertion of the pin to full tracking capability is 20 ms max.

The SHUTDOWN pin is asserted at any time except during the initial power on sequence or the wakeup sequence from a previous SHUTDOWN state.

Table 15. SHUTDOWN Pin

SHUTDOWN pin	Sensor Operating Mode
High	Hibernate mode
Low	Tracking, nap, or sleep mode

MOTION Pin

The MOTION output reports the present operating mode of the sensor. When the MOTION pin is asserted, the sensor can process SPI commands. When the MOTION pin is deasserted, the sensor is in nap, sleep, or hibernate mode and cannot process SPI commands.

Table 16. MOTION Pin

MOTION pin	Sensor Operating Mode
High	Tracking mode
Low	Nap, sleep, or hibernate mode

In addition, the MOTION pin serves as a startup indicator. The pin is asserted when the initial power on sequence or the wakeup sequence from SHUTDOWN state is complete. If the mouse is in motion during startup, the MOTION pin stays high; if the mouse is not moving, the MOTION pin goes low after 4 seconds.

For the CYONS1001, CYONS1001G, and CYONS1001U only, the MOTION pin can also be used as an indicator of the sensor's readiness to report x/y data. For these models, the sensor pulls MOTION low when it is processing the Read x/y command, and set MOTION high again when it is ready to report data. Using this feature, designers can use the rising edge of the MOTION line as a signal to poll the sensor. This allows the mouse to poll the sensor at the highest possible rate.

EXTCFG Pin

The EXTCFG pin enables a factory test mode that manufacturers can use to verify laser output power for safety compliance purposes. The pin is held low by an internal 4K - 8K ohm pull down resistor, but is driven high to enable factory test mode.

To enable factory test mode, drive the EXTCFG pin high at power up. When the power on sequence is complete, the sensor asserts the MOTION pin, indicating the device is ready to accept configuration data from the external controller over the SPI bus. The test command sequence is described in "[Laser Output Power Test Procedure](#)" on page 15.

To re-enable the normal mode of operation after testing, set the EXTCFG pin low or no-connect at power up.

Table 17. EXTCFG Pin

EXTCFG pin	Sensor Operating Mode
High	Enables factory test mode
Low or NC	Normal operating mode

Laser Safety Considerations

CYONS1001x laser navigation sensors and the CYONSLENS1001 lens are designed and tested to enable manufacturers to achieve eye safety certification with minimal effort. This section provides guidelines for complying with the Class 1 emission requirements of IEC/EN 60825-1.

Laser Output Power

The CYONS1001x sensor package contains an integrated VCSEL and drive circuitry. Before shipping, Cypress adjusts the laser output power to eye-safe levels, taking into account specified variations in supply voltage, temperature, lens transmission, and VCSEL polarization, and factors such as VCSEL aging and test equipment accuracy. The output remains within eye-safe limits under reasonably foreseeable single-faults, as required by the IEC standard.

From the perspective of a manufacturer, laser emission remains within the Class 1 limit, as defined in IEC 60825-1, Edition 1.2, 2001-08, provided the following requirements are met.

- The supply voltage applied to the sensor must be in the range of 2.7 to 3.6V.
- The operating temperature must be between 5 and 45 °C.
- A CYONSLENS1001 must be properly installed over the sensor.

In addition, the following requirements must be met to prevent access to radiation levels that exceed the Class 1 limit:

- The laser output power must not be increased by any means, including firmware, hardware, or mechanical modifications to the sensor or lens.
- The sensor housing must be designed in such a way that the CYONSLENS1001 cannot be opened without the use of a tool.
- If the mouse is equipped with batteries, the housing must be designed to prevent access to laser energy when the battery cover is removed.

It is the responsibility of the manufacturer to ensure these conditions are always met and to demonstrate end-product compliance to the appropriate regulatory standards.

Laser Output Power Test Procedure

To verify the factory calibration, maximum output power is measured using the following procedure:

1. With power to the sensor off, drive the EXTCFG pin high, or temporarily tie the pin to DVDD.
2. Apply power and wait for the sensor to assert the MOTION pin. This indicates that the sensor is ready to accept configuration data from the external controller over the SPI bus.
3. Assert the SPI slave-select line and send the following configuration bytes to sensor through the SPI interface. A minimum delay of 50 μ s must be added between bytes.

```
<0x03> <0x01> <0x00> <0x18> <0xFF> <0x02>  
<0x04> <0x00> <0xA7> <0x00> <0xFF> <0x00>
```

The sensor locks the laser to the programmed power limit with continuous wave (CW) output. The sensor provides tracking data if queried, but the tracking performance is poor due to the test mode. After testing, the sensor must be power cycled with the EXTCFG pin low or not connected to ensure optimal tracking.

Registration Assistance

Cypress can provide assistance to customers who wish to obtain registration. Supporting documentation, including a verification test procedure to demonstrate end-product compliance with IEC and CDRH requirements is available. For further information, contact a Cypress representative.

Mechanical Design Considerations

This section provides the mechanical information required to incorporate the CYONS1001x sensor and CYONSLENS1001 lens into a mouse design.

Housing Design Safety Considerations

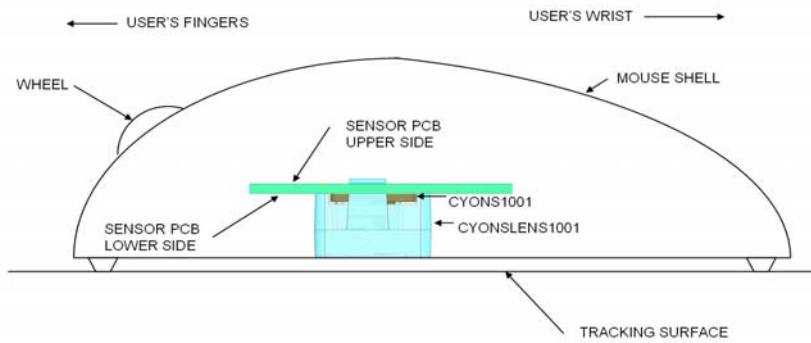
The housing must be designed to ensure compliance with Class 1 laser safety standards. To prevent exposure to radiation levels that exceed Class 1 limits, the mouse must be designed such that it cannot be disassembled without the use of a tool. In

addition, if the mouse is battery powered, the housing must be designed to prevent access to laser energy from when changing batteries.

Orientation of PCB in a Mouse Application

Figure 9 shows the orientation of the sensor PCB in a standard mouse application. The sensor is mounted on a small PCB. Typically, the PCB is oriented sensor side down in the device housing.

Figure 9. Sensor PCB Orientation

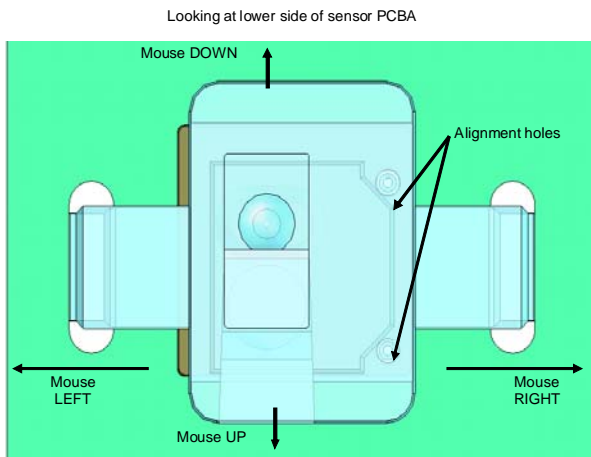


Orientation of Sensor on PCB

Figure 10 shows the correct assignment of "mouse UP," "mouse DOWN," "mouse LEFT," and "mouse RIGHT" motion. The UP and DOWN directions are reversed because the sensor side of the PCB faces down.

Note that this diagram does not apply to the CYONS1001T sensor, which is typically mounted beneath a trackball. To maintain correct x/y orientation, the y report of the CYONS1001T is inverted (opposite sign) with respect to the other sensors.

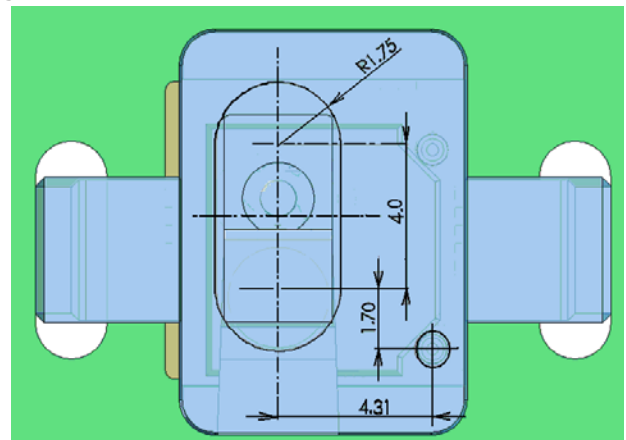
Figure 10. Orientation of Sensor on PCB



Sensor Illumination Aperture

The illumination aperture must be properly sized to ensure light is not blocked as it enters or exits the sensor assembly. The minimum dimensions of the aperture are shown in Figure 11. Dimensions are in mm, referenced to the center of the lens alignment pin.

Figure 11. Illumination Aperture



PCB Requirements

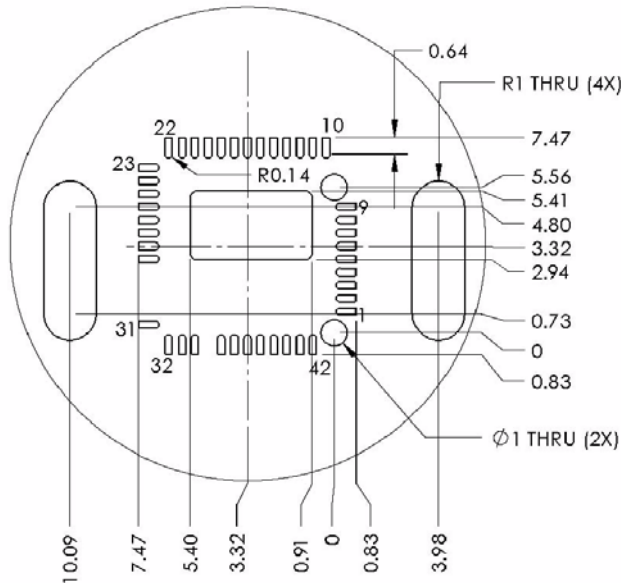
Figure 12 shows the mechanical requirements for the PCB. The board requires:

- Two clearance holes 1.00 mm in diameter for the lens alignment pins.
- Two slots for the clip legs of the lens. The radii of these slots are also 1.00 mm, giving the slot a width of 2.00 mm.

The holes and the slots must be clear of other components on both sides of the PCB.

Land pad architecture and spacing are consistent with JEDEC MO-220 (52-lead QFN). The L-shaped feature inside the array of lands must be soldered to the tab on the bottom of the sensor package and connected to the DGND signal of the PCBA. Also, the entire area within the sensor land pads must be kept free of exposed copper.

Figure 12. PCB Mechanical Features

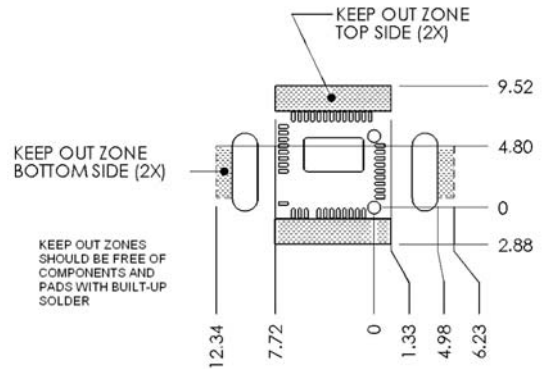


PCB Keepout Zones

Figure 13 shows the PCB keepout zones. The keepouts on the sensor side of the board prevent interference with the CYONSLENS1001 lens after it is mounted on the sensor. The keepouts on the opposite side of the board prevent interference

with the lens clips. The keepouts must be free of both components and solder build-up.

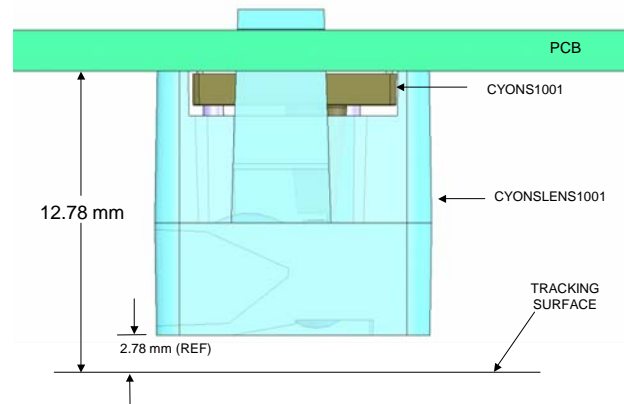
Figure 13. PCB Keepout Zones



PCB Mounting Height

The distance between the tracking surface and the sensor must be controlled. For optimal performance, the lower edge of the PCB must be positioned 12.78 ± 0.25 mm from the tracking surface, as shown in Figure 14. At this distance, the lower plane of the lens is typically 2.78 mm above the tracking surface. Deviations from the specified PCB-to-tracking surface distance degrade tracking performance and lift detection.

Figure 14. PCB Mounting Height



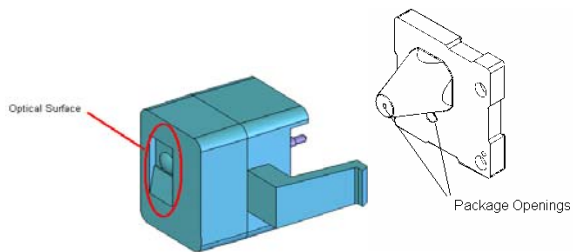
Recommended Assembly Instructions

Handling Guidelines

To maximize yield and performance, follow the handling guidelines listed below.

- Do not touch the optical surfaces of the CYONSLENS1001. Hold lenses only by their outer edges.
- Do not allow debris or dust to enter the optical aperture on the top of the package. Do not remove the protective tape over the package openings until immediately before the lens is attached.
- Do not wash the sensor PCBA after the laser sensor has been installed. The protective tape prevents moisture and dust from entering the sensor; however, it is not designed to withstand pressurized washing fluids.

Figure 15. Handling Guidelines



Manufacturing Process

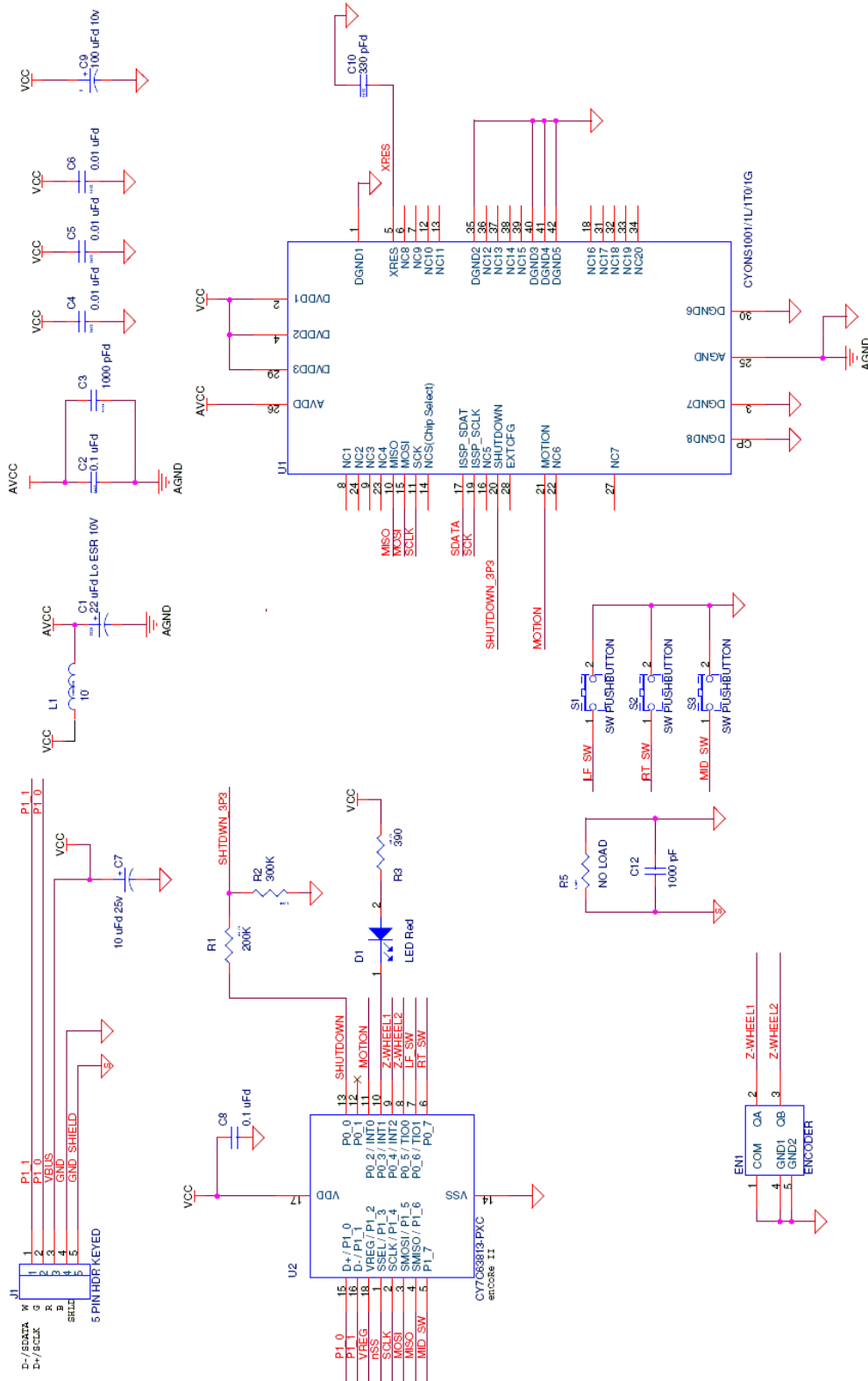
The CYONS1001x laser navigation sensors are designed to simplify the production process. Specifically,

- The sensors are rated at 2kV ESD, so standard ESD practices are acceptable.
- The laser is integrated into the sensor package, so there is no need for laser handling, lead forming, or installation.
- The laser is precalibrated, so there is no need to adjust laser output power

While different designs may require different manufacturing procedures, a recommended manufacturing process for a mouse is:

1. Collect sensor PCBA components (no need for select-at-test components).
2. Place laser sensor and passive components on sensor PCBA using a no-wash solder paste.
3. Solder components to PCBA.
4. Snap a CYONSLENS1001 lens over the laser sensor.
5. Install the laser sensor PCBA into the system housing.
6. Test and ship.

Appendix 1: Wired Mouse Reference Schematic



Ordering Information

Part Number	Package	Package Type	Operating Range
CYONS1001U-LBXC	42-lead PQFN	PQFN (plastic quad flat) leadless, Pb free	5–45 °C
CYONS1001G-LBXC	42-lead PQFN	PQFN (plastic quad flat) leadless, Pb free	5–45 °C
CYONS1001-LBXC	42-lead PQFN	PQFN (plastic quad flat) leadless, Pb free	5–45 °C
CYONS1001L-LBXC	42-lead PQFN	PQFN (plastic quad flat) leadless, Pb free	5–45 °C
CYONS1001T0-LBXC	42-lead PQFN	PQFN (plastic quad flat) leadless, Pb free	5–45 °C

Part Number	Package	Operating Range
CYONSLENS1001-C	Lens	5–45 °C

Document History Page

Document Title: CYONS1001x OvationONS™ Laser Navigation Sensor				
Document Number: 001-06398				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	419897	See ECN	XSJ	New data sheet
*A	429039	See ECN	XSJ	Updated pinout & parameter tables, power supply diagram, and packaging diagrams
*B	435541	See ECN	XSJ	Updated the ordering information, features, and functional descriptions; Changed nSS (chip select) to NCS; Cleaned up block diagram
*C	464397	See ECN	XSJ	Added Eye Safety (Class 1) notation; Updated product & technology names; Added PCB LAND pads to Mechanical section
*D	486184	See ECN	XSJ	Updated the operating conditions table, DC electrical table, AC electrical table, pin description table, power supply connections, block and package diagrams; Added lens part number
*E	906420	04/03/2007	XSJ	Updated DC Electrical characteristics table.
*F	1160423	06/18/07	XSJ, FJZ, SOZ	Combined data sheet and User Guide into one document (data sheet document). Added sections on OptiCheck, resolution control modes, firmware updates, additional SPI commands, etc. Updated description, feature list, block diagram, technical specifications and wired and wireless mouse schematics.
*G	1202224	See ECN	FJZ/AESA	Updated feature list. Updated tables 1, 2, 3, 4, 5, 6, 9, 10, 12, 13, 16, and 17. Updated figures 4, 5, 6, 7, 8, 9, and 12. Updated SPI timing, removed transient current supply spec. Updated Appendix 1, added Appendix 2. Corrected miscellaneous punctuation, grammar, and typographical errors. Updated text to make consistent with Tables and Figures.
*H	1338563	See ECN	XSJ, FJZ	Updated pin description table 2. Changed "CYONS1001LENS" reference to "CYONSLENS1001". Added Package Diagram and Package Specification Number.
*I	1684564	See ECN	XSJ, FJZ	Added CYONS1001U part number/description
*J	2035787	See ECN	FJZ/AESA	Changed mechanical drawings, added minor corrections

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